

## HD74LS74A

# Dual D-type Positive Edge-triggered Flip-Flops (with Preset and Clear)

REJ03D0415-0300 Rev.3.00 Jul.22.2005

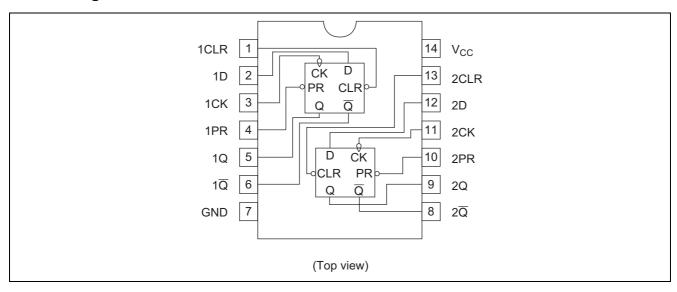
#### **Features**

• Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS74AP	DILP-14 pin	PRDP0014AB-B (DP-14AV)	Р	_
HD74LS74AFPEL	SOP-14 pin (JEITA)	PRSP0014DF-B (FP-14DAV)	FP	EL (2,000 pcs/reel)
HD74LS74ARPEL	SOP-14 pin (JEDEC)	PRSP0014DE-A (FP-14DNV)	RP	EL (2,500 pcs/reel)

Note: Please consult the sales office for the above package availability.

#### **Pin Arrangement**



#### **Function Table**

	Inp	Out	put		
Preset	Clear	Clock	D	Q	Q
L	Н	X	X	Н	L
Н	L	X	X	L	Н
L	L	X	X	H*	H*
Н	Н	<b>↑</b>	Н	Н	L
Н	Н	<b>↑</b>	L	L	Н
Н	Н	L	X	$Q_0$	$\overline{Q}_0$

H; high level, L; low level, X; irrelevant, ↑; transition from low to high level,

## **Absolute Maximum Ratings**

Item	Symbol	Ratings	Unit
Supply voltage	V <sub>CC</sub>	7	V
Input voltage	V <sub>IN</sub>	7	V
Power dissipation	P <sub>T</sub>	400	mW
Storage temperature	Tstg	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

#### **Recommended Operating Conditions**

Item Supply voltage		Symbol	Min	Тур	Max	Unit	
		V <sub>CC</sub>	4.75	5.00	5.25	V	
Output current		I <sub>OH</sub>	_	_	-400	μΑ	
		I <sub>OL</sub>	_	_	8	mA	
Operating temperature		Topr	-20	25	75	°C	
Clock frequency		f <sub>clock</sub>	0	_	25	MHz	
Pulse width	Clock High	t <sub>w</sub>	25	_	_	20	
	Clear Preset	t <sub>w</sub>	25	_	_	ns	
Setup time "H" Data		t <sub>su</sub>	20↑	_	_	20	
Setup time	"L" Data	t <sub>su</sub>	20↑	_	_	ns	
Hold time		t <sub>h</sub>	5↑	_	_	ns	

Note: ↑; The arrow indicates the rising edge.

Q<sub>0</sub>; level of Q before the indicated steady-state input conditions were established.

 $<sup>\</sup>overline{Q}_0$ ; complement of  $\overline{Q}_0$  or level of Q before the indicated steady-state input conditions were established.

<sup>\*;</sup>This configuration is nonstable, that is, it will not persist when preset and clear inputs return to their inactive (high) level.

#### **Electrical Characteristics**

 $(Ta = -20 \text{ to } +75 \text{ }^{\circ}\text{C})$ 

It	em	Symbol	min.	typ.*	max.	Unit	Condition		
Input voltage		V <sub>IH</sub>	2.0	_	_	V			
input voita	ige	V <sub>IL</sub>	_	_	0.8	V			
		V <sub>OH</sub>	2.7	_	_	V	$V_{CC} = 4.75 \text{ V}, \text{ V}_{IH} = 2 \text{ V}, \text{ V}_{IL} = 0.8 \text{ V}, \\ I_{OH} = -400  \mu\text{A}$		
Output vo	tage		_	_	0.5	V	$I_{OL} = 8 \text{ mA}$ $V_{CC} = 4.75 \text{ V}, V_{IL} = 0.8 \text{ V},$		
		V <sub>OL</sub>	_	_	0.4	V	I <sub>OL</sub> = 4 mA V <sub>IH</sub> = 2 V		
	D		_	_	20				
	Clear	] ,	_	_	40		V 525 V V 2.7 V		
	Preset	I <sub>IH</sub>	_	_	40	μΑ	$V_{CC} = 5.25 \text{ V}, V_I = 2.7 \text{ V}$		
	Clock		_	_	20				
	D	I <sub>IL</sub>	_	_	-0.4	mA	V <sub>CC</sub> = 5.25 V, V <sub>I</sub> = 0.4 V		
Input	Clear		_	_	-0.8				
current	Preset		_	_	-0.8				
	Clock		_	_	-0.4				
	D		_	_	0.1				
	Clear	] ,	_	_	0.2	mA	V 5.05.V. V 7.V		
	Preset	l <sub>l</sub>	_	_	0.2		$V_{CC} = 5.25 \text{ V}, V_{I} = 7 \text{ V}$		
	Clock		_	_	0.1				
Short-circucurrent	uit output	los	-20	_	-100	mA	V <sub>CC</sub> = 5.25 V		
Supply cu	rrent	I <sub>CC</sub> **	_	4	8	mA	V <sub>CC</sub> = 5.25 V		
Input clam	p voltage	$V_{IR}$			-1.5	V	$V_{CC} = 4.75 \text{ V}, I_{IN} = -18 \text{ mA}$		

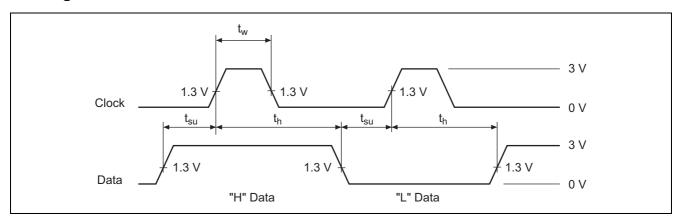
Notes:  $^*V_{CC} = 5 \text{ V}, \text{ Ta} = 25^{\circ}\text{C}$ 

### **Switching Characteristics**

 $(V_{CC} = 5 \text{ V}, \text{Ta} = 25^{\circ}\text{C})$ 

Item	Symbol	Inputs	Outputs	min.	typ.	max.	Unit	Condition
Maximum clock frequency	f <sub>max</sub>			25	33		MHz	C 15 pF
Propagation delay time	t <sub>PLH</sub>	Clear, Clock	Q, Q	_	13	25	ns	$C_L = 15 \text{ pF},$ $R_L = 2 \text{ k}\Omega$
Fropagation delay time	t <sub>PHL</sub>	or Preset		_	25	40	ns	

## **Timing Definition**

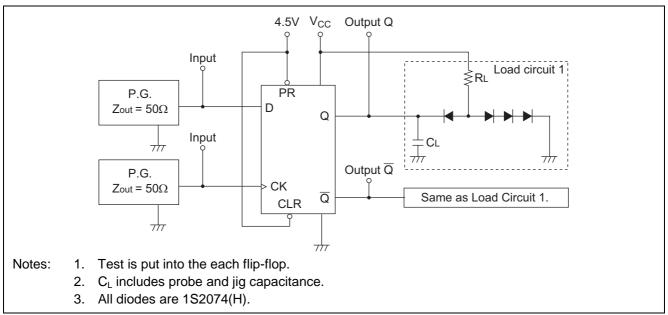


<sup>\*\*</sup> With all output open,  $I_{CC}$  is measured with the Q and  $\overline{Q}$  outputs high in turn. At the time of measurement, the clock input is grounded.

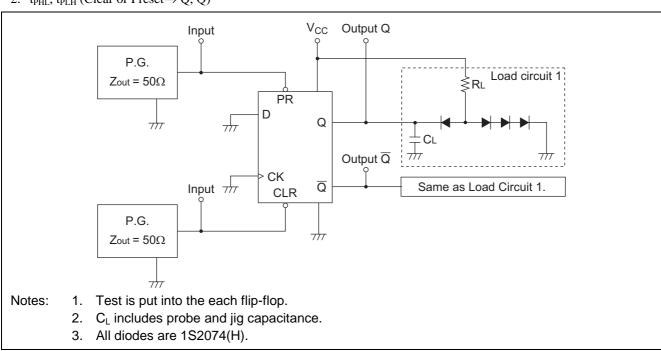
#### **Testing Method**

#### **Test Circuit**

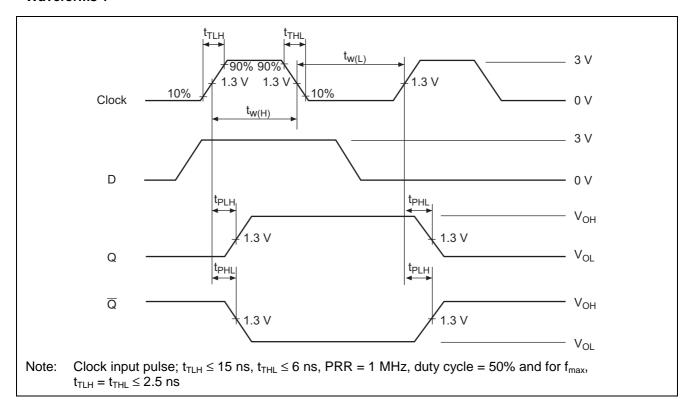
1.  $f_{\text{max}}$ ,  $t_{\text{PLH}}$ ,  $t_{\text{PHL}}$  (Clock $\rightarrow$ Q,  $\overline{Q}$ )



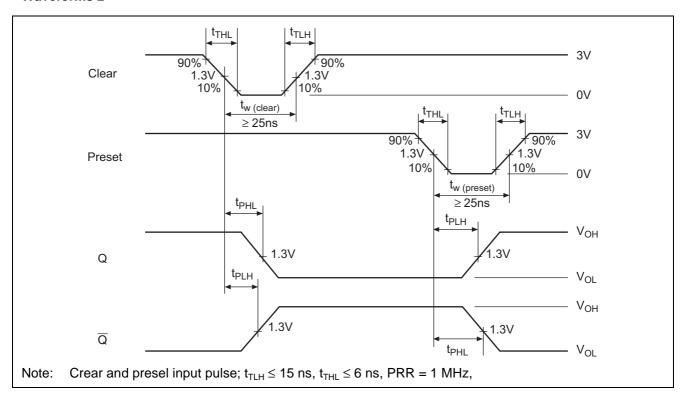
2.  $t_{PHL}$ ,  $t_{PLH}$  (Clear or Preset $\rightarrow$  Q,  $\overline{Q}$ )



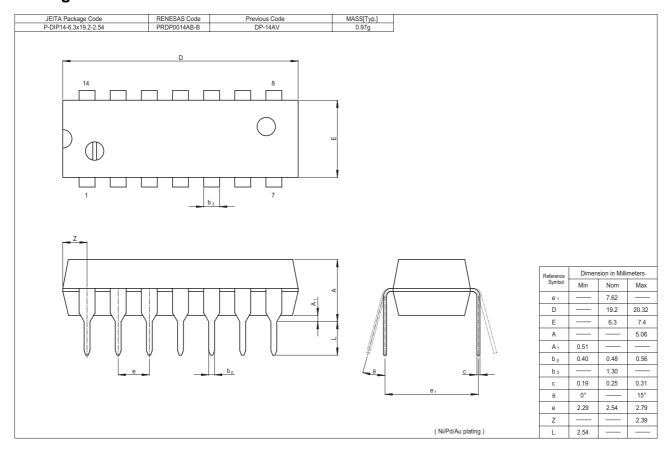
#### Waveforms 1

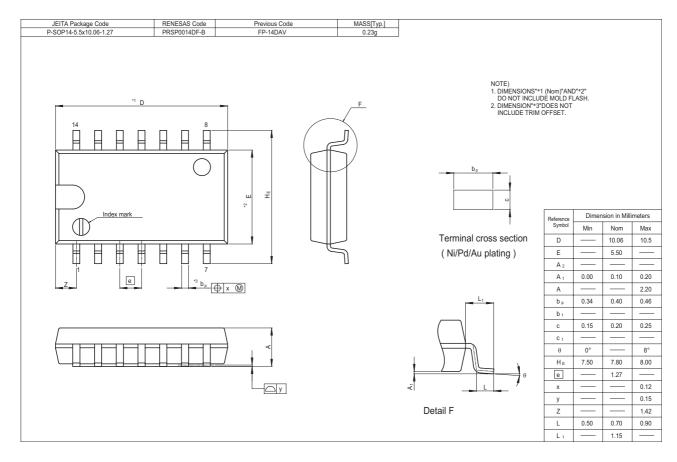


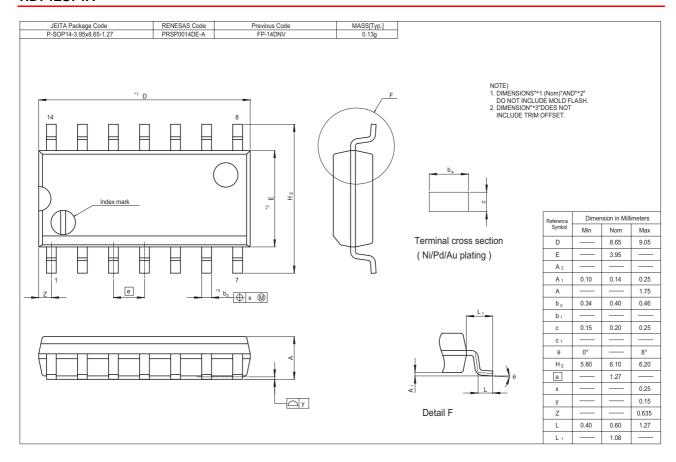
#### Waveforms 2



#### **Package Dimensions**







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